

High Speed Infrared Emitting Diodes, 940 nm, GaAlAs, MQW



DESCRIPTION

VSMB2943SLX01 is an infrared, 940 nm, side looking emitting diode in GaAlAs multi quantum well (MQW) technology with high radiant power and high speed, molded in clear, untinted plastic package (with lens) for surface mounting (SMD).

APPLICATIONS

- IrDA compatible data transmission
- Miniature light barrier
- Photointerrupters
- Optical switch
- Remote control
- IR touch panels

FEATURES

- Package type: surface mount
- Package form: side view
- Dimensions (L x W x H in mm): 2.3 x 2.55 x 2.3
- AEC-Q101 qualified
- Peak wavelength: $\lambda_p = 940$ nm
- High reliability
- High radiant power
- High radiant intensity
- Angle of half intensity: $\phi = \pm 25^\circ$
- Low forward voltage
- Suitable for high pulse current operation
- Package matches with detector VEMD2023SLX01 and VEMT2023SLX01
- Floor life: 4 weeks, MSL 2a, acc. J-STD-020
- Material categorization: For definitions of compliance please see www.vishay.com/doc?99912

AUTOMOTIVE
GRADE

RoHS
COMPLIANT
HALOGEN
FREE
GREEN
(5-2008)

PRODUCT SUMMARY

COMPONENT	I_e (mW/sr)	ϕ (deg)	λ_p (nm)	t_r (ns)
VSMB2943SLX01	20	± 25	940	15

Note

- Test conditions see table "Basic Characteristics"

ORDERING INFORMATION

ORDERING CODE	PACKAGING	REMARKS	PACKAGE FORM
VSMB2943SLX01	Tape and reel	MOQ: 3000 pcs, 3000 pcs/reel	Side view

Note

- MOQ: minimum order quantity

ABSOLUTE MAXIMUM RATINGS ($T_{amb} = 25^\circ\text{C}$, unless otherwise specified)

PARAMETER	TEST CONDITION	SYMBOL	VALUE	UNIT
Reverse voltage		V_R	5	V
Forward current		I_F	100	mA
Peak forward current	$t_p/T = 0.5$, $t_p = 100 \mu\text{s}$	I_{FM}	200	mA
Surge forward current	$t_p = 100 \mu\text{s}$	I_{FSM}	1	A
Power dissipation		P_V	160	mW
Junction temperature		T_j	100	$^\circ\text{C}$
Operating temperature range		T_{amb}	-40 to +85	$^\circ\text{C}$
Storage temperature range		T_{stg}	-40 to +100	$^\circ\text{C}$
Soldering temperature	according figure 9, J-STD-020	T_{sd}	260	$^\circ\text{C}$
Thermal resistance junction/ambient	J-STD-051, leads 7 mm, soldered on PCB	R_{thJA}	250	K/W

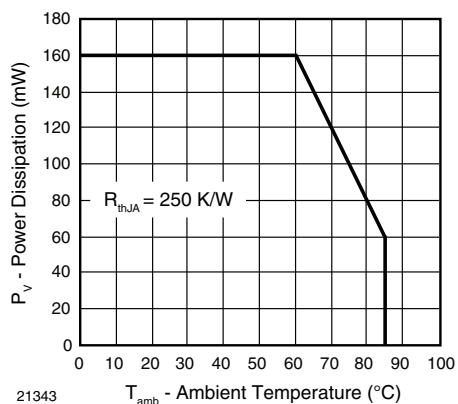


Fig. 1 - Power Dissipation Limit vs. Ambient Temperature

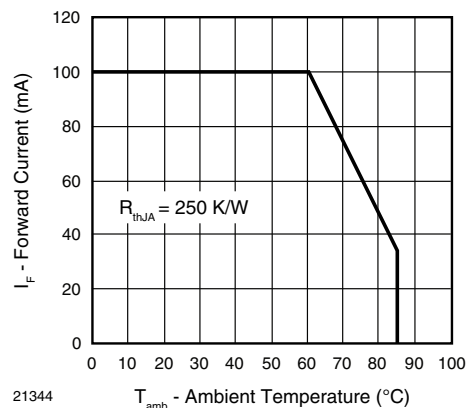


Fig. 2 - Forward Current Limit vs. Ambient Temperature

BASIC CHARACTERISTICS ($T_{amb} = 25\text{ }^{\circ}\text{C}$, unless otherwise specified)						
PARAMETER	TEST CONDITION	SYMBOL	MIN.	TYP.	MAX.	UNIT
Forward voltage	$I_F = 100\text{ mA}$, $t_p = 20\text{ ms}$	V_F	1.15	1.35	1.6	V
	$I_F = 1\text{ A}$, $t_p = 100\text{ }\mu\text{s}$	V_F		2.2		V
Temperature coefficient of V_F	$I_F = 1\text{ mA}$	TK_{VF}		-1.8		mV/K
	$I_F = 100\text{ mA}$	TK_{VF}		-1.1		mV/K
Reverse current		I_R	Not designed for reverse operation			μA
Junction capacitance	$V_R = 0\text{ V}$, $f = 1\text{ MHz}$, $E = 0\text{ mW/cm}^2$	C_J		70		pF
Radiant intensity	$I_F = 100\text{ mA}$, $t_p = 20\text{ ms}$	I_e	10	20	30	mW/sr
	$I_F = 1\text{ A}$, $t_p = 100\text{ }\mu\text{s}$	I_e		170		mW/sr
Radiant power	$I_F = 100\text{ mA}$, $t_p = 20\text{ ms}$	ϕ_e		40		mW
Temperature coefficient of radiant power	$I_F = 1\text{ mA}$	TK_{ϕ_e}		-1.1		%/K
	$I_F = 100\text{ mA}$	TK_{ϕ_e}		-0.51		%/K
Angle of half intensity		ϕ		± 25		deg
Peak wavelength	$I_F = 30\text{ mA}$	λ_p	920	940	960	nm
Spectral bandwidth	$I_F = 30\text{ mA}$	$\Delta\lambda$		25		nm
Temperature coefficient of λ_p	$I_F = 30\text{ mA}$	TK_{λ_p}		0.25		nm/K
Rise time	$I_F = 100\text{ mA}$, 20 % to 80 %	t_r		15		ns
Fall time	$I_F = 100\text{ mA}$, 20 % to 80 %	t_f		15		ns
Cut-off frequency	$I_{DC} = 70\text{ mA}$, $I_{AC} = 30\text{ mA pp}$	f_c		23		MHz

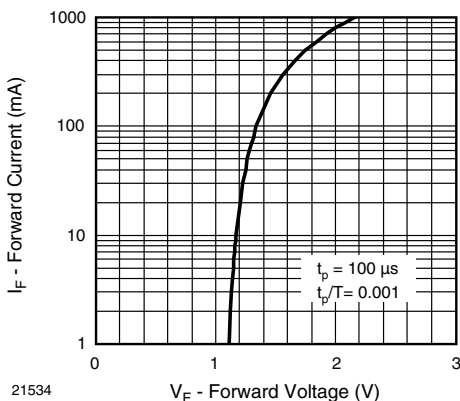
BASIC CHARACTERISTICS ($T_{amb} = 25\text{ }^{\circ}\text{C}$, unless otherwise specified)


Fig. 3 - Forward Current vs. Forward Voltage

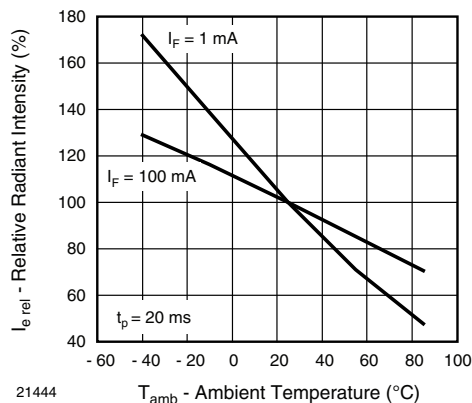


Fig. 6 - Relative Radiant Intensity vs. Ambient Temperature

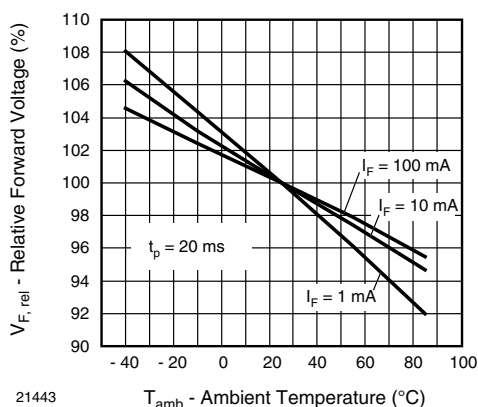


Fig. 4 - Relative Forward Voltage vs. Ambient Temperature

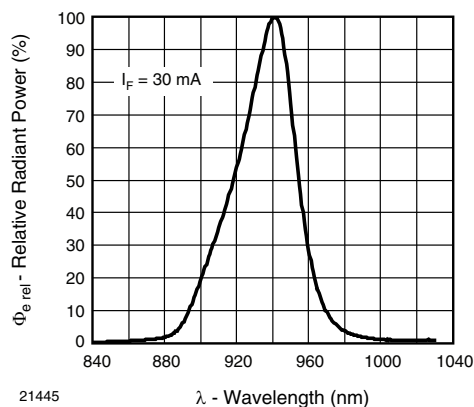


Fig. 7 - Relative Radiant Power vs. Wavelength

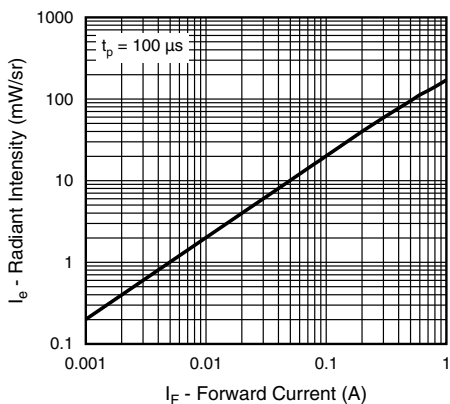


Fig. 5 - Radiant Intensity vs. Forward Current

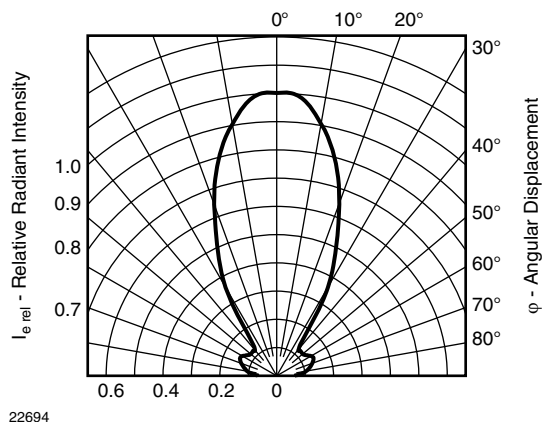


Fig. 8 - Relative Radiant Intensity vs. Angular Displacement

SOLDER PROFILE

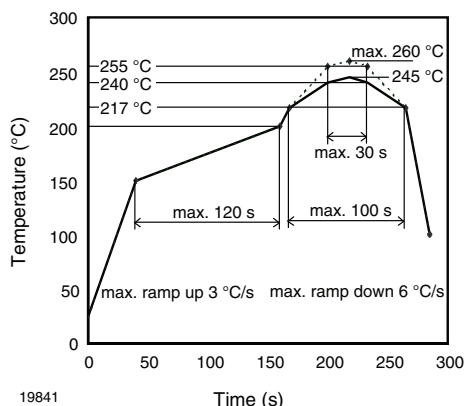
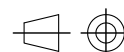
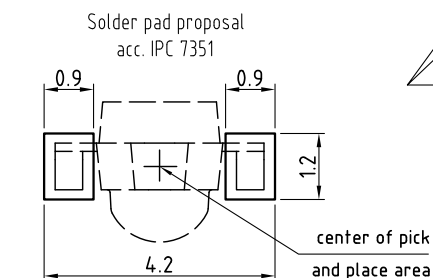
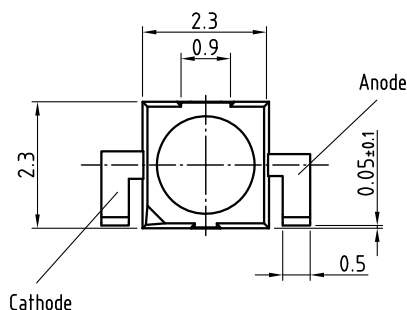
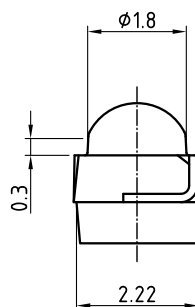
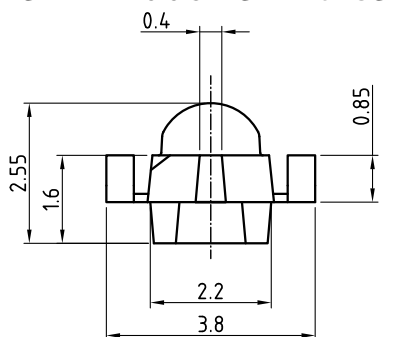


Fig. 9 - Lead (Pb)-free Reflow Solder Profile acc. J-STD-020

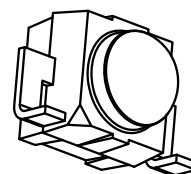
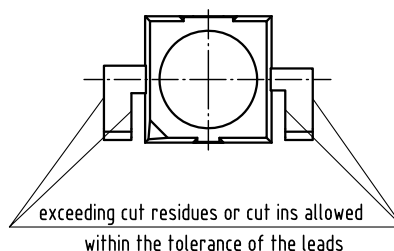
PACKAGE DIMENSIONS in millimeters: VSMB2943SL



technical drawings
according to DIN
specifications

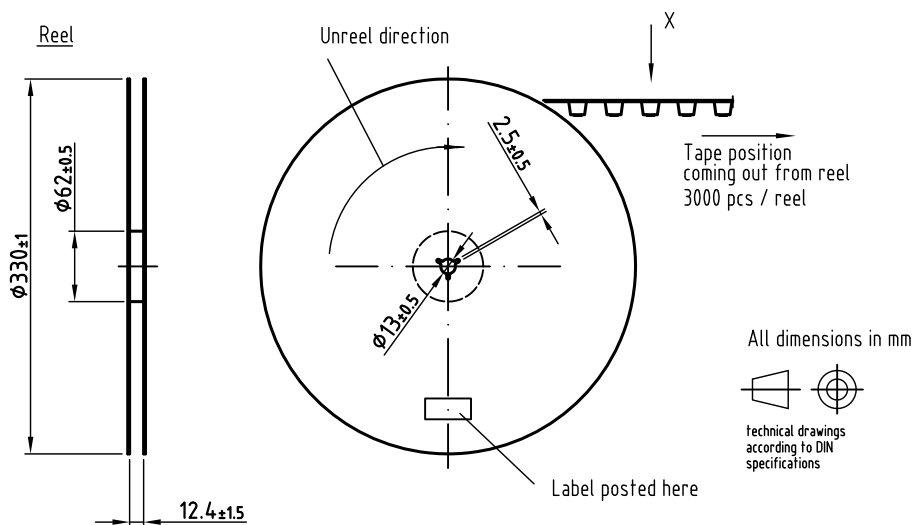
Dimensions in mm

Not indicated tolerances ± 0.2

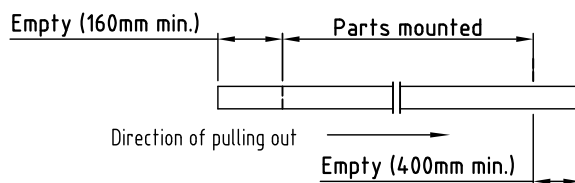


Drawing refers to following types: VSMB2943SLX01
VSMF2893SLX01
VSMB2948SL
VEMD2x23SLX01

Drawing-No.: 6.544-5410.02-4
Issue: prel. 03.08.12

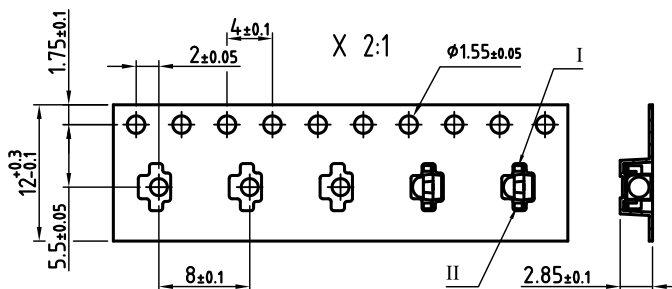
TAPING AND REEL DIMENSIONS in millimeters: VSMB2943SL


Leader and trailer tape:



Terminal position in tape

Device	Lead I	Lead II
VSMB2943SLX01	Cathode	Anode
VSMF2893SLX01		
VSMB2948SL		
VEMD2023SLX01		
VEMD2523SLX01	Collector	Emitter
VEMT2023SLX01		
VEMT2523SLX01	Anode	Cathode
VSMY2853SL		



Drawing refers to following types: see table
Reel dimensions and tape

Drawing-No.: 9.800-5123.01-4
Issue: prel; 01.02.13



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